IPC ASSOCIATION ELECTRONICS	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under international and Pan-American copyright conventions.				der both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1	IPC Web Site for Information on IPC-1752 Standard  http://www.ipc.org/IPC-175x  Form Typ Distribute								ials and Mfg Information						
Supplier	· Information														
Company name* Company				pany unique ID			Unique ID Authority				Response Date*				
nsemi											2024-05	2024-05-17			
Contact Na	ame	Title - Contact			]	Phone - Contact*				Email - Contact*					
Product-E	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized	d Representative*	Title - Representative			]	Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
	Requester Item Number		Number	Mfr Item Name			Effective Da	te Versio	on I	Manufacturing Site		Weight*	UOM	Unit Type	
	SS13FP			30V 1A Schottky Rectif			2024-05-17		,	TSCBE		21.80046	mg	Each	
Manufac	cturing Proccess Informa	ation												í	
Terminal Plating / Grid Array Material Te			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temper		Temperatu	ature Max Time at Peak Ten		ture Numb	er of Reflow Cyc	les		
Matte Tin (Sn) - annealed CU Alloy 1					260		С	30	secor	nds 3					
Comments															
evel 1 - ma	aximum time at peak tempera	ture during sol	dering is 10-3	0 seconds											
or more i	information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU  RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier shave provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	-En								

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	1.3299	mg	Supplier	Iron (Fe)	7439-89-6		0.0013	mg
I			Supplier	Copper (Cu)	7440-50-8		1.3282	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0004	mg
Die	2.022	mg	Supplier	Titanium (Ti)	7440-32-6		0.003	mg
			Supplier	Silver (Ag)	7440-22-4		0.0752	mg
			Supplier	Silicon (Si)	7440-21-3		1.9251	mg
			В	Nickel (Ni)	7440-02-0		0.0186	mg
Die Attach Solder	0.41096	mg	Supplier	Silver (Ag)	7440-22-4		0.0103	mg
			A	Lead (Pb)	7439-92-1	7a	0.3801	mg
			Supplier	Tin (Sn)	7440-31-5		0.0205	mg
Lead Frame	12.3086	mg	Supplier	Iron (Fe)	7439-89-6		0.0123	mg
			Supplier	Copper (Cu)	7440-50-8		12.2926	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0037	mg
Mold Compound-Black	5.7288	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5757	mg
-			Supplier	Carbon Black (C)	1333-86-4		0.0286	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.8953	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.2292	mg
Plating	2.0E-4	mg	Supplier	Tin (Sn)	7440-31-5		0.0002	mg